Materials Declaration

Package	SOT 23
Body Size	--
LeadCount	3
Option	Pb-free

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2	81.0	4.43 E-03	509009
Resin	16.1	8.81 E-04	101173
Sb2O3	1.4	7.66 E-05	8798
Brominated epoxy	1.0	5.47 E-05	6284
Carbon Black	0.5	2.74 E-05	3142
Subtotal		5.47 E-03	628406

Molding Compound

Item	PPM	Method
Pb	None Detected	EPA Method 3052. Draft IEC62321. ICP-OES.
Cd	None Detected	EPA Method 3052. Draft IEC62321. ICP-OES.
Hg	None Detected	EPA Method 3052. Draft IEC62321. ICP-OES.
Cr+6	None Detected	EPA Method 3060A. Draft IEC62321. UV-VIS
PBB	None Detected	EPA Method 3540C. Draft IEC62321. GC/MS-D.
PBDE	None Detected	EPA Method 3540C. Draft IEC62321. GC/MS-D.

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Fe	56.7	1.32 E-03	151544
Ni	41.5	9.65 E-04	110918
Mn	0.8	1.86 E-05	2138
Co	0.5	1.16 E-05	1336
Si	0.3	6.98 E-06	802
Cr	0.1	2.33 E-06	267
Al	0.1	2.33 E-06	267
Subtotal		2.33 E-03	267273

Die Attach Paste

Item	PPM	Method
Pb	Not Detected	EPA Method 3052. Draft IEC62321. ICP-OES.
Cd	Not Detected	EPA Method 3052. Draft IEC62321. ICP-OES.
Hg	Not Detected	EPA Method 3052. Draft IEC62321. ICP-OES.
Cr+6	Not Detected	EPA Method 3060A. Draft IEC62321. UV-VIS
PBB	Not Detected	EPA Method 3540C. Draft IEC62321. GC/MS-D.
PBDE	Not Detected	EPA Method 3540C. Draft IEC62321. GC/MS-D.

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	2.35 E-05	2700

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	2.25 E-04	25800

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	1.00 E-04	11487

Chip

	% of Chip	Weight (g)	PPM
Si	100	5.00 E-04	57441

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Epoxy Resin	80	4.80 E-05	5514
Silicon Dioxide	15	9.00 E-06	1034
Aromatic Amine	5	3.00 E-06	345
Subtotal		6.00 E-05	6893

Package Totals

Weight (g)	PPM
8.70 E-03	1000000

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ANALOG DEVICES

Materials Declaration

Package	SOT 23
Body Size	--
LeadCount	3
Option	with Pb

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2	67.20	3.68 E-03	421542
Epoxy Cresol Novolac	20.00	1.09 E-03	125459
Phenol Novolac	7.00	3.83 E-04	43911
Sb2O3	3.00	1.64 E-04	18819
Brominated epoxy	2.50	1.37 E-04	15682
Carbon black	0.30	1.64 E-05	1882
Subtotal		5.47 E-03	627294

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Fe	56.7	1.32 E-03	151276
Ni	41.5	9.65 E-04	110722
Mn	0.8	1.86 E-05	2134
Co	0.5	1.16 E-05	1334
Si	0.3	6.98 E-06	800
Cr	0.1	2.33 E-06	267
Al	0.1	2.33 E-06	267
Subtotal		2.33 E-03	266801

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	2.35 E-05	2695

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	2.04 E-04	23395
Pb	15	3.60 E-05	4128
Subtotal		2.40 E-04	27523

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	1.00 E-04	11467

Chip

	% of Chip	Weight (g)	PPM
Si	100	5.00 E-04	57340

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Silver	80	4.80 E-05	5505
Epoxy Resin	15	9.00 E-06	1032
Aromatic Amine	5	3.00 E-06	344
		6.00 E-05	6881

Molding Compound

Item	PPM	Method
Pb	None Detected	EPA Method 3052. Draft IEC62321. ICP-OES.
Cd	None Detected	EPA Method 3052. Draft IEC62321. ICP-OES.
Hg	None Detected	EPA Method 3052. Draft IEC62321. ICP-OES.
Cr+6	None Detected	EPA Method 3060A. Draft IEC62321. UV-VIS
PBB	None Detected	EPA Method 3540C. Draft IEC62321. GC/MS-D.
PBDE	None Detected	EPA Method 3540C. Draft IEC62321. GC/MS-D.

Die Attach Paste

Item	PPM	Method
Pb	Not Detected	EPA Method 3052. Draft IEC62321. ICP-OES.
Cd	Not Detected	EPA Method 3052. Draft IEC62321. ICP-OES.
Hg	Not Detected	EPA Method 3052. Draft IEC62321. ICP-OES.
Cr+6	Not Detected	EPA Method 3060A. Draft IEC62321. UV-VIS
PBB	Not Detected	EPA Method 3540C. Draft IEC62321. GC/MS-D.
PBDE	Not Detected	EPA Method 3540C. Draft IEC62321. GC/MS-D.

Package Totals

Weight (g)	PPM
8.72 E-03	1000000

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ANALOG DEVICES

Materials Declaration

Package	SOT 23 - Isolated Backside
Body Size	--
LeadCount	3
Option	Pb-free

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2	81.0	4.43 E-03	509169
Resin	16.1	8.81 E-04	101205
Sb2O3	1.4	7.66 E-05	8800
Brominated epoxy	1.0	5.47 E-05	6286
Carbon Black	0.5	2.74 E-05	3143
Subtotal		5.47 E-03	628603

Molding Compound

Item	PPM	Method
Pb	Not Detected	EPA Method 3052. ICP-OES
Cd	Not Detected	EPA Method 3052. ICP-OES
Hg	Not Detected	EPA Method 3052. ICP-OES
Cr+6	Not Detected	EPA Method 3060A & 7196A. UV-VIS
PBB	Not Detected	EPA Method 3550C/3540C. GC/MS.
PBDE	Not Detected	EPA Method 3550C/3540C. GC/MS.

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Fe	56.7	1.32 E-03	151576
Ni	41.5	9.65 E-04	110942
Mn	0.8	1.86 E-05	2139
Co	0.5	1.16 E-05	1337
Si	0.3	6.98 E-06	802
Cr	0.1	2.33 E-06	267
Al	0.1	2.33 E-06	267
Subtotal		2.33 E-03	267330

Die Attach Paste

Item	PPM	Method
Pb	Not Detected	EPA Method 3051A/3052. ICP-OES
Cd	Not Detected	EPA Method 3051A/3052. ICP-OES
Hg	Not Detected	EPA Method 3051A/3052. ICP-OES
Cr+6	Not Detected	EPA Method 3060A & 7196A. UV-VIS
PBB	Not Detected	EPA Method 3550C/3540C. GC/MS.
PBDE	Not Detected	EPA Method 3550C/3540C. GC/MS.

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	2.35 E-05	2701

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	2.25 E-04	25808

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	1.00 E-04	11491

Chip

	% of Chip	Weight (g)	PPM
Si	100	4.98 E-04	57172

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Epoxy Resin	46	2.76 E-05	3172
Silicon Dioxide	46	2.76 E-05	3172
Curing Agent	8	4.80 E-06	552
Subtotal		6.00 E-05	6895

Package Totals

Weight (g)	PPM
8.70 E-03	1000000

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ANALOG DEVICES

ADI Proprietary

Materials Declaration

Package	SOT 23 - Isolated Backside
Body Size	--
LeadCount	3
Option	with Pb

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2	81.0	4.43 E-03	508274
Resin	16.1	8.81 E-04	101027
Sb2O3	1.4	7.66 E-05	8785
Brominated epoxy	1.0	5.47 E-05	6275
Carbon Black	0.5	2.74 E-05	3137
Subtotal		5.47 E-03	627498

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Fe	56.7	1.32 E-03	151310
Ni	41.5	9.65 E-04	110747
Mn	0.8	1.86 E-05	2135
Co	0.5	1.16 E-05	1334
Si	0.3	6.98 E-06	801
Cr	0.1	2.33 E-06	267
Al	0.1	2.33 E-06	267
Subtotal		2.33 E-03	266861

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	2.35 E-05	2696

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	2.04 E-04	23392
Pb	15	3.60 E-05	4128
Subtotal		2.40 E-04	27520

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	1.00 E-04	11470

Chip

	% of Chip	Weight (g)	PPM
Si	100	4.98 E-04	57071

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Epoxy Resin	46	2.76 E-05	3166
Silicon Dioxide	46	2.76 E-05	3166
Curing Agent	8	4.80 E-06	551
Subtotal		6.00 E-05	6883

Molding Compound

Item	PPM	Method
Pb	Not Detected	EPA Method 3052. ICP-OES
Cd	Not Detected	EPA Method 3052. ICP-OES
Hg	Not Detected	EPA Method 3052. ICP-OES
Cr+6	Not Detected	EPA Method 3060A & 7196A. UV-VIS
PBB	Not Detected	EPA Method 3550C/3540C. GC/MS
PBDE	Not Detected	EPA Method 3550C/3540C. GC/MS

Die Attach Paste

Item	PPM	Method
Pb	Not Detected	EPA Method 3051A/3052. ICP-OES
Cd	Not Detected	EPA Method 3051A/3052. ICP-OES
Hg	Not Detected	EPA Method 3051A/3052. ICP-OES
Cr+6	Not Detected	EPA Method 3060A & 7196A. UV-VIS
PBB	Not Detected	EPA Method 3550C/3540C. GC/MS
PBDE	Not Detected	EPA Method 3550C/3540C. GC/MS

Package Totals

Weight (g)	PPM
8.72 E-03	1000000

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ANALOG DEVICES